AT5010 Series

Multilayer Chip Antenna

AT5010-A3R0HAA

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖ Wide bandwidth
- ❖ RoHS compliant

Applications

- ❖Bluetooth/Wireless LAN/Home RF
- ❖ISM band 2.4GHz applications

Specifications

Part Number	Frequency Range (MHz)	Peak Gain (XZ-V)	Average Gain (XZ-V)	VSWR	Impedance
AT5010 -A3R0HAA_	2400 ~ 2500	2.2 dBi typ.	0.1 dBi typ.	2 max.	50

Q'ty/Reel (pcs) : 2,000 pcs
Operating Temperature Range : -40 ~ +85 °C
Storage Temperature Range : -40 ~ +85 °C
Storage Period : 12 months max.
Power Capacity : 3W max.

Part Number

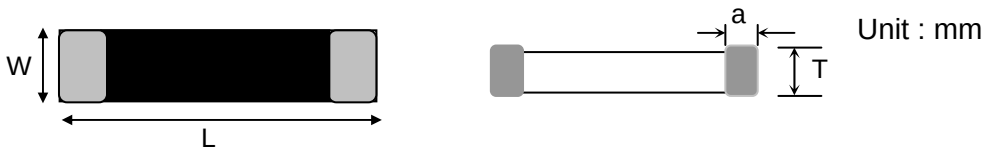
AT	5010	-	A	3R0	HAA	□	□
①	②		③	④	⑤	⑥	⑦

① Type	AT : Antenna	② Dimensions (L × W)	5.0× 1.0 mm
③ Material Code	A	④ Frequency Range	3R0=3000MHz
⑤ Specification Code	HAA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

Terminal Configuration

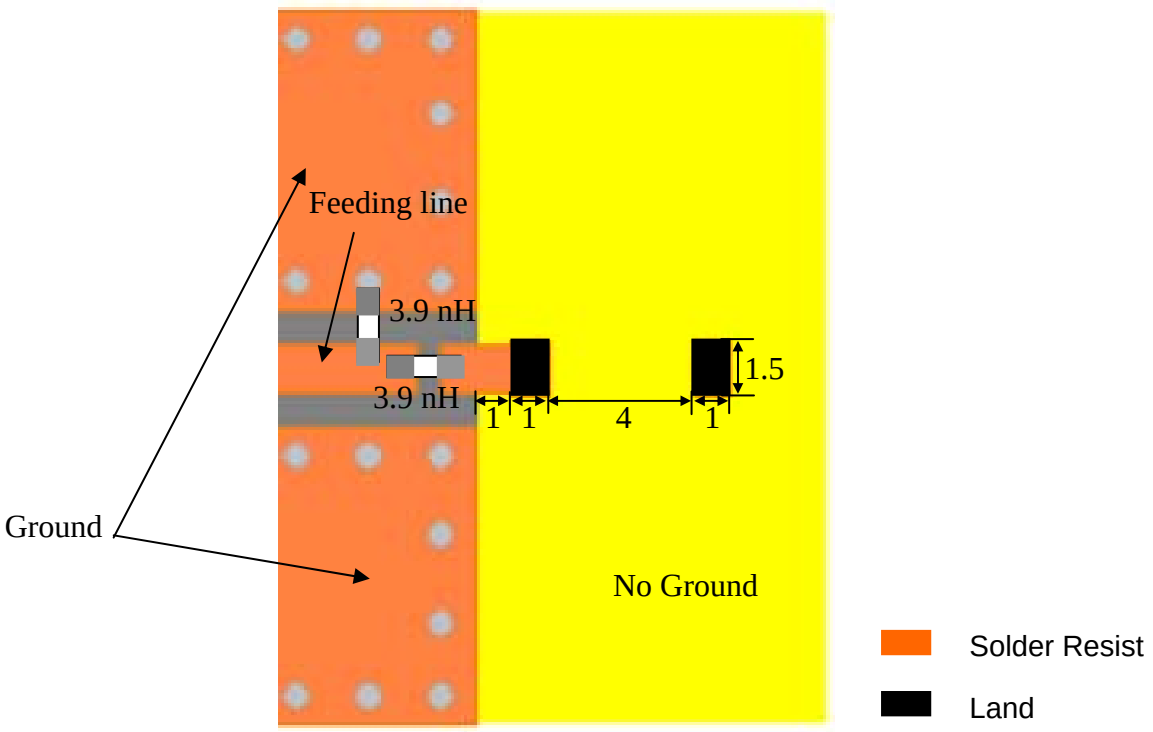
No.	Terminal Name	No.	Terminal Name
①	Feeding Point or NC	②	Feeding Point or NC

Dimensions and Recommended PC Board Pattern



Mark	L	W	T	a
Dimensions	5.0±0.2	1.0±0.2	1.0±0.2	0.5±0.2

❖With Matching Circuits (Unit in mm)

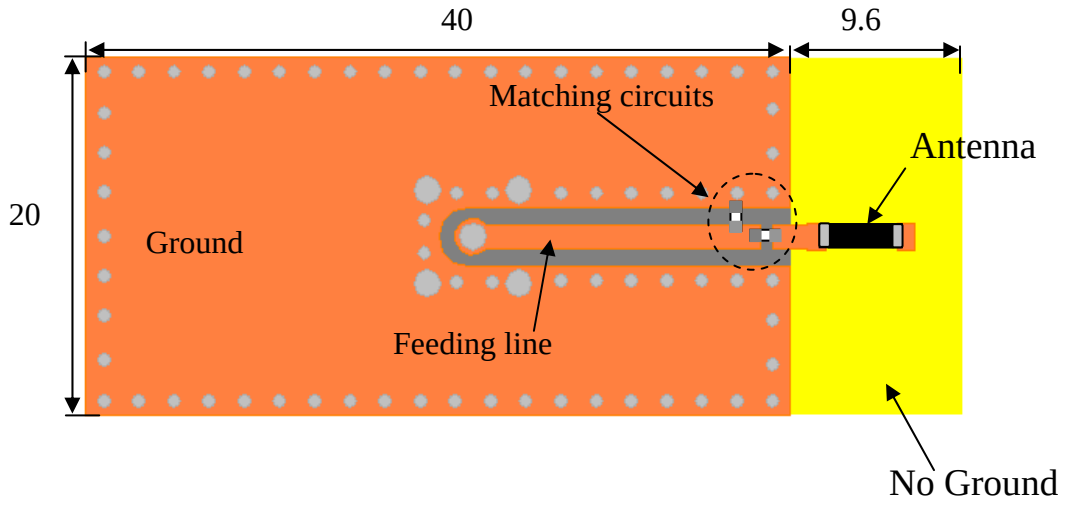


(Matching circuit and component values will be different, depending on PCB layout)

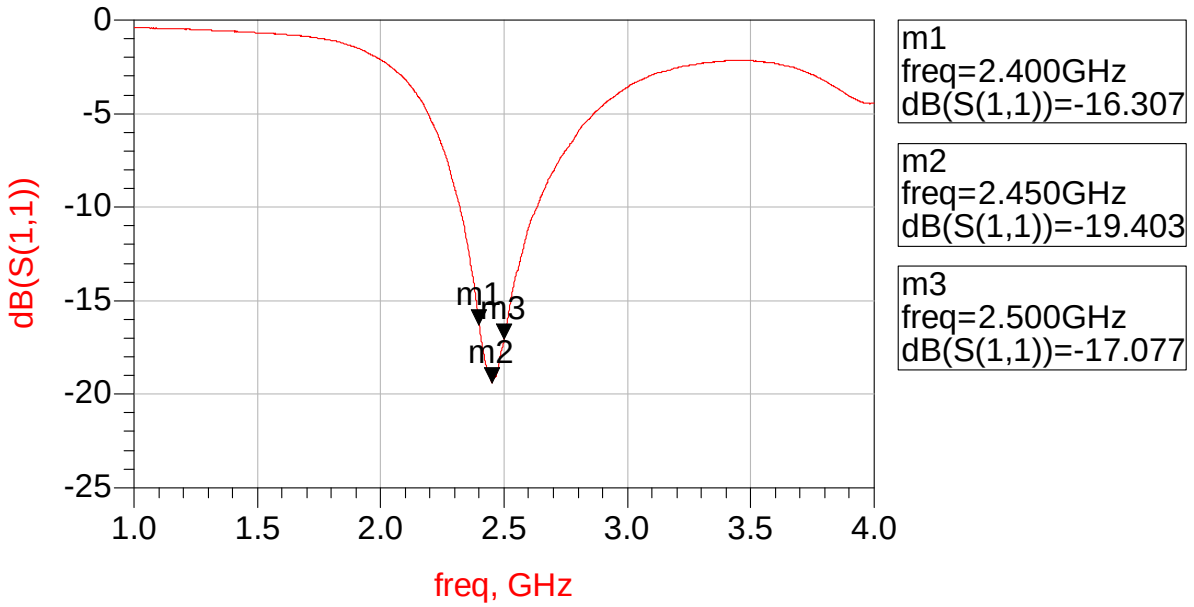
*Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

Typical Electrical Characteristics (T=25°C)

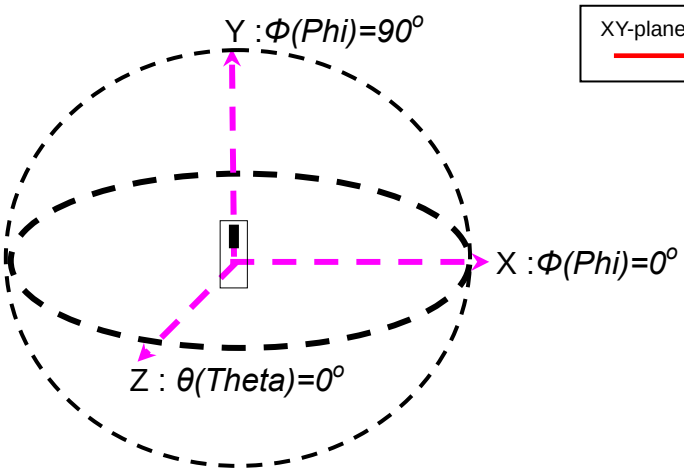
❖Test Board (Unit in mm)



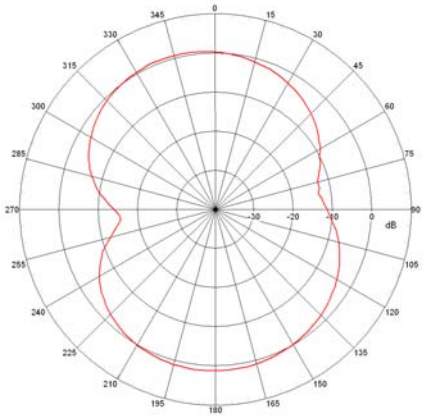
❖Return Loss / With Matching Circuits



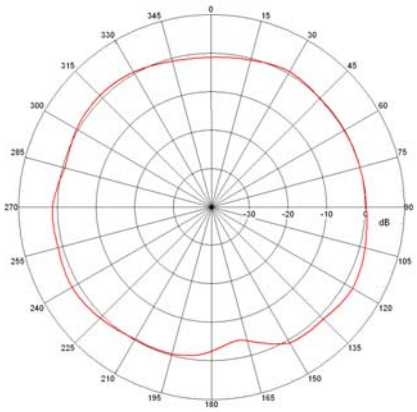
❖Radiation Patterns - (Antenna Efficiency 70%@ 2.4GHz; 74%@2.45GHz ; 64%@2.5GHz)



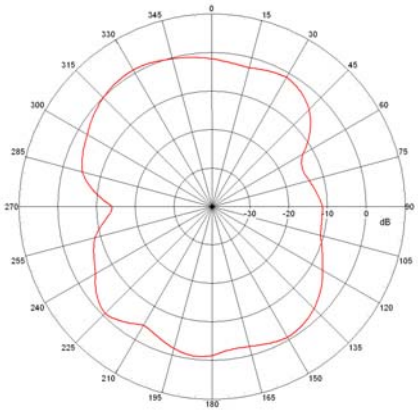
XY-plane @2450MHz
Total



XZ-plane @2450MHz
Total

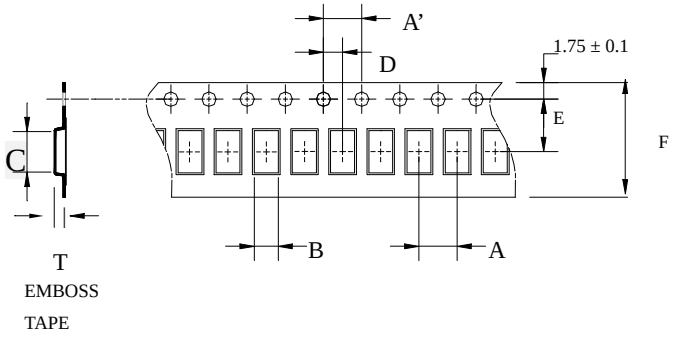


YZ-plane @2450MHz
Total



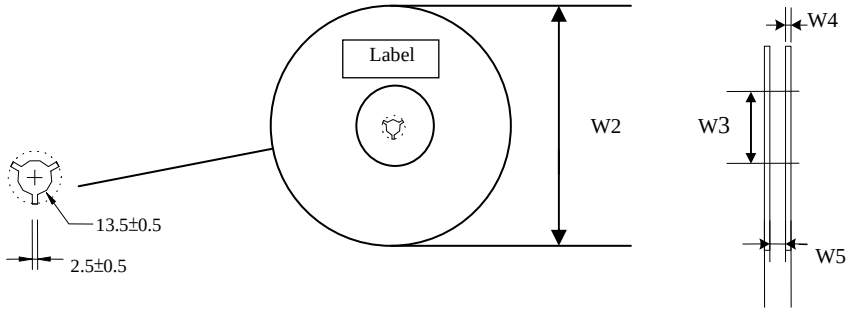
Taping Specifications

❖Tape & Reel Dimensions (Unit: mm) vs. Quantity (pcs)



Type	A	A'	B	C	D	E	F	T	Quantity/per reel	Tape material
AT5010	4.0± 0.10	4.0± 0.10	1.25± 0.10	5.35± 0.10	2.0± 0.10	5.5± 0.10	12.0± 0.15	1.15± 0.10	2,000pcs	Plastic (Embossed)

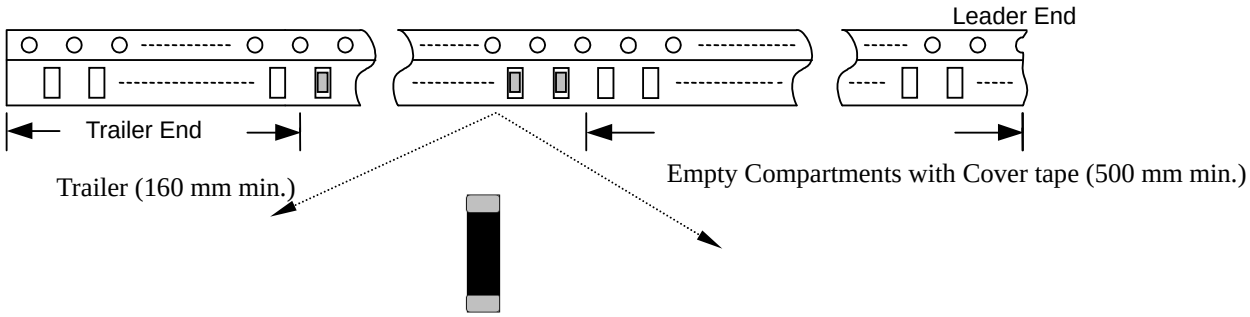
❖Reel Dimensions (Unit: mm)



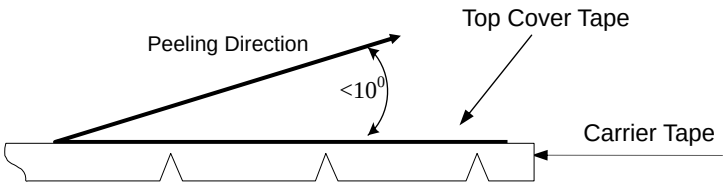
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	W2	W3	W4	W5
AT5010	178±1	60±1	1.4±0.2	17±0.5

❖Leader and Trailer Tape



❖Peel-off Force



Peel-off force should be in the range of 0.2 – 1.20 N at a peel-off speed of 300±10 mm/min .

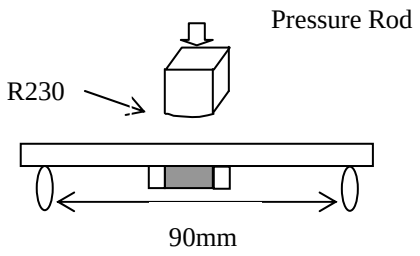
❖Storage Conditions

(1) Temperature: 5 ~35℃, relative humidity (RH): 45~75%.
(2) Non-corrosive environment.

Notes

❖The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

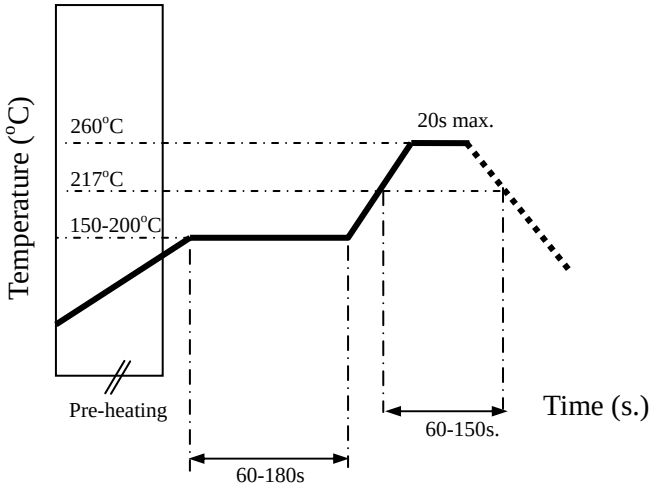
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	1. No apparent damage 2. More than 95% of the terminal electrode shall be covered with new solder	1. Preheat: 120± 5 °C 2. Solder: 245± 5°C for 5± 1 sec
Soldering strength (Termination Adhesion)	1. 10N minimum	1. Solder specimen onto test jig. 2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	1. No apparent damage	1. Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. 2. Apply a bending force of 1mm deflection. 
Heat/Humidity Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: 85± 2°C 2. Humidity: 90% ~ 95% RH 3. Duration: 1000±48hrs 4. Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	1. No apparent damage 2. Fulfill the electrical specification after test	1. One cycle/step 1：125 ± 5°C for 30 min step 2：- 40 ± 5°C for 30 min 2. No of cycles：100 3. Recovery:1-2 hrs
Low Temperature Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: -40± 5 °C 2. Duration: 500 ±24hrs 3. Recovery: 1-2hrs

Soldering Conditions

❖**Typical Soldering Profile for Lead-free Process**

Reflow Soldering :



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